



Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
------------	--	---------------------------	--

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID				
Mindspeed Technologies Inc	N/A	N/A	2013-02-28					
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Cynthia Ong	Program Manager	949-579-5515	cynthia.ong@mindspeed.com					
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *	Supplier Comments or URL for Additional Information				
Amy Teng	Quality Engineer	604-6328114	amy.teng@mindspeed.com					
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
M21131-22	M21131-22	35FCBGA 1156	2010-08-26	B	ASE, Taiwan	16,208.45	mg	EACH
Alternate Recommendation		NA		Alternate Item Comments	NA			

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Eutectic 63/37	N/A	4	220 C	40 seconds	3
Comments					
N/A					

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Locked

RoHS Material Composition Declaration

Declaration Type *

Simplified

RoHS Directive
2002/95/EC

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration *

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance *

Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
											-	+	
M21131-22	TIM	151.31	mg	C	GROUP-C	Others	Trade Secret		15.13	mg			99,993
				C	GROUP-C	Alumina	01344-28-1		136.18	mg			900,00
	Underfill	56.86	mg	C	GROUP-C	Silicon dioxide	60676-86-0		26.1556	mg			459,99
				C	GROUP-C	Amine type accelerator	Trade Secret		2.843	mg			49,999
				C	GROUP-C	Phenolic resin	9003-35-4		11.372	mg			199,99
				C	GROUP-C	Additives	Trade Secret		2.843	mg			49,999
				C	GROUP-C	Bisphenol F type liquid	9003-36-5		11.372	mg			199,99
				C	GROUP-C	Carbon black	1333-86-4		0.5686	mg			9,999.9
				C	GROUP-C	Bisphenol A type liquid	25068-38-6		1.7058	mg			29,999
	Bump	0.51	mg	A	Lead/Lead Compound	Pb	7439-92-1		0.19	mg			372,54
				C	GROUP-C	Sn	7440-31-5		0.32	mg			627,45
	Heatslug	11,426	mg	C	GROUP-C	Chrome	Trade Secret		5.71	mg			499.73
				B	Nickel/Nickel Compound	Nickel	7440-02-0		68.56	mg			4,229.8
				C	GROUP-C	Copper	7440-50-8		11,351.73	mg			993,49
	Solder Ball	1,017.2	mg	A	Lead/Lead Compound	Pb	7439-92-1		376.36	mg			369,99
				C	GROUP-C	Sn	7440-31-5		640.84	mg			630,00
	Substrate	2,864.01	mg	C	GROUP-C	Resin	Trade Secret		21.66	mg			7,562.8
						N, N-dimethylformamide	68-12-2		2.74	mg			169.04
				C	GROUP-C	organic material	Trade Secret		3.75	mg			1,309.3
				C	GROUP-C	Copper	7440-50-8		1,199.02	mg			418,65
				C	GROUP-C	E-Glass Fabric	65997-17-3		643.95	mg			224,84
				C	GROUP-C	Others (Organic Compound)	Trade Secret		5.42	mg			1,892.4
				C	GROUP-C	Epoxy Resin	26265-08-7		482.96	mg			168,63

				Cyclohexane	108-94-1		13.71	mg			845.85
C	GROUP-C			Sn	7440-31-5		3.22	mg			1,124.2
C	GROUP-C			Initiator (Organic Comp	Trade Secret		2.03	mg			708.79
C	GROUP-C			other epoxy resin	Trade Secret		5	mg			1,745.8
C	GROUP-C			Solvent	112-15-2, 647		17.6	mg			6,145.2
C	GROUP-C			Coal tar naphtha	64742-94-5		2.74	mg			956.70
C	GROUP-C			Others	Trade Secret		219.44	mg			76,619
C	GROUP-C			Additive (Organic Comp	Trade Secret		0.68	mg			237.42
A	Lead/Lead Compound			Pb	7439-92-1		1.89	mg			659.91
C	GROUP-C			Fillers	14808-60-7		160.99	mg			56,211
C	GROUP-C			methyl octanoate	67762-90-7		3.75	mg			1,309.3
C	GROUP-C			Pigment (Organic Comp	Trade Secret		0.68	mg			237.42
C	GROUP-C			Filler	2530-83-8, 77		19.63	mg			6,854.0
C	GROUP-C			Bisphenol A epoxy resin	25068-38-6		53.15	mg			18,557
Die	692.56	mg		C	GROUP-C						
							692.56	mg			999,99